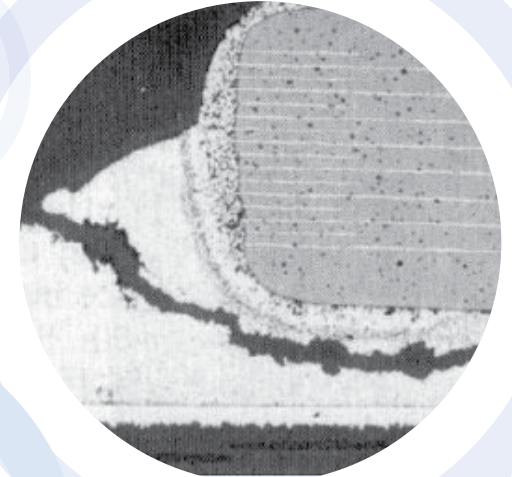




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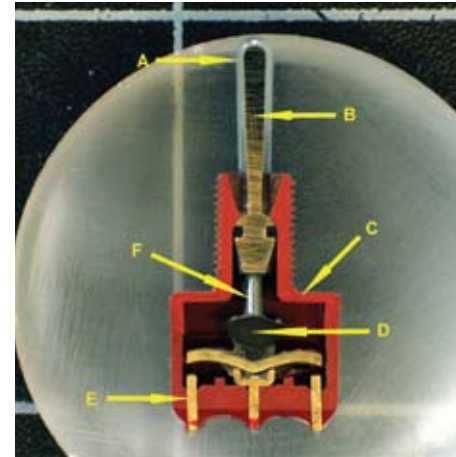
Destructive Testing

of PCBs, electronic components,
assemblies and materials

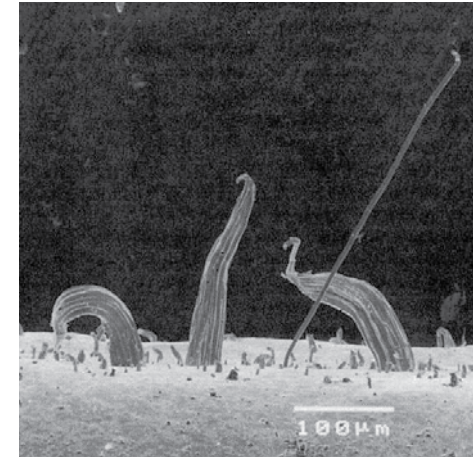
“Tests can be carried out to investigate a part’s failure, in order to understand its structural performance or material behavior. These tests are generally much easier to carry out, yield more information, and are easier to interpret than nondestructive testing. Sometimes they are the only option to enable us to offer a definitive answer.”



Soldertec Manager,
Dr Wayne Lam



Microsection



Tin whiskers

Our Solutions

PCB laminates Testing

- IPC6012
- Solderability testing using wetting balance
- Cleanliness checked using contaminometer
- Tin Whiskering
- Failure analysis using SEM & EDX
- Testing for black pad on ENIG

Electronic Components testing

- Solderability testing using wetting balance
- Cleanliness checked using contaminometer
- Failure analysis using SEM & EDX
- Bond wire testing
- Tin Whiskering
- Counterfeit detection
- De-capping of ICs

Electronic Assemblies

- Failure analysis using Dye & Pry, SEM & EDX
- Cleanliness checked using contaminometer
- RoHS compliance
- China-RoHS compliance
- Salt spray & corrosion testing
- Tin Whiskering

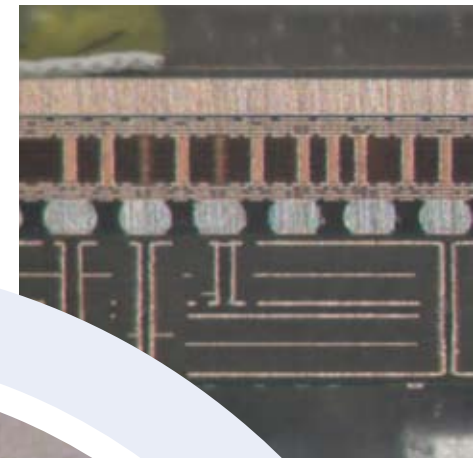
Materials

- Surface Insulation Resistance and Electromigration
- RoHS compliance
- China-RoHS compliance
- Wet chemical analysis
- IR, UV/Vis spectroscopy
- Metals analysis using ICP & AAS
- Particle size measurements
- Crystal structure analysis using XRD

Decapping



LBGA



intermetallic

